

What is claimed is:

1. A method of manufacturing a ceramic thick-film printed circuit board, comprising the steps of:

forming a printed pattern on a substrate; and

5 firing the printed pattern,

wherein a layer comprising a resin having a thickness ranging from 0.15 to 2 μm is formed on the surface of the substrate prior to the printed pattern forming step.

2. The method of manufacturing a ceramic thick-film printed circuit board of claim 1, wherein the thickness of the layer is controlled by a mixing ratio of resins having a same chemical structure and different molecular weights.

3. The method of manufacturing a ceramic thick-film printed circuit board of claim 1, wherein a temperature increasing rate ranges from 80 to 15 120 $^{\circ}\text{C}/\text{min}$ in the firing step.

4. The method of manufacturing a ceramic thick-film printed circuit board of claim 3, wherein the temperature increasing rate is adjusted according to a molecular weight of the resin.

5. The method of manufacturing a ceramic thick-film printed circuit board of claim 1, wherein a fired film has a thickness ranging from 5 to 22 μm . 20

6. The method of manufacturing a ceramic thick-film printed circuit board of claim 5, wherein the thickness of the fired film is adjusted according to a molecular weight of a binder resin contained in a printing paste.

7. The method of manufacturing a ceramic thick-film printed circuit board of claim 1, wherein a printing paste having a solvent content ranging from 8 to 25 wt% is used in the printed pattern forming step. 25

8. The method of manufacturing a ceramic thick-film printed circuit

~~demanded~~

5 ranging from 0.15 to 0.5 μm or a maximum surface roughness R_{max} ranging

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